

HARD WAFER GRINDING METHOD

ABSTRACT

A hard wafer grinding method includes a rough grinding step of forming a section along the diameter of a hard wafer into a centrally recessed shape by roughly grinding the hard wafer such that a central part of the hard wafer is thinner than a peripheral part of the hard wafer, a finish grinding step of expanding a ground area of the hard wafer from the peripheral part in an annular shape to the central part while dressing lower surfaces of finish grinding stones by the peripheral part of the hard wafer of the centrally recessed shape after the rough grinding, then setting the whole of a radius part of the hard wafer as the ground area, and further finish-grinding the hard wafer so as to obtain a predetermined thickness.

[Fig. 5]